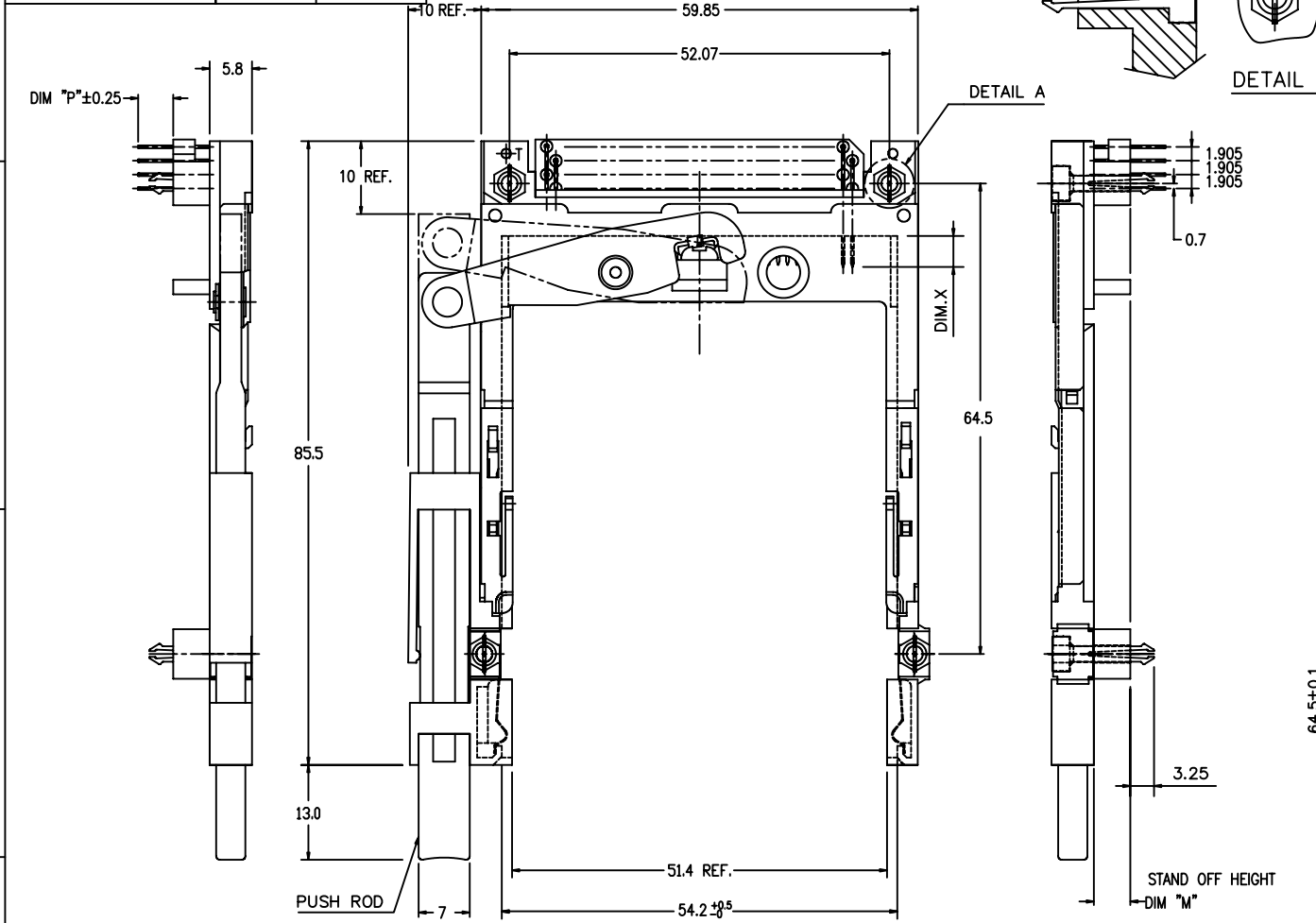


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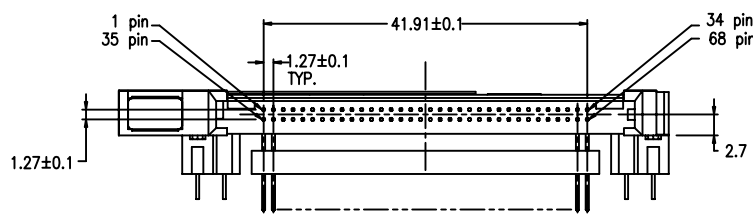
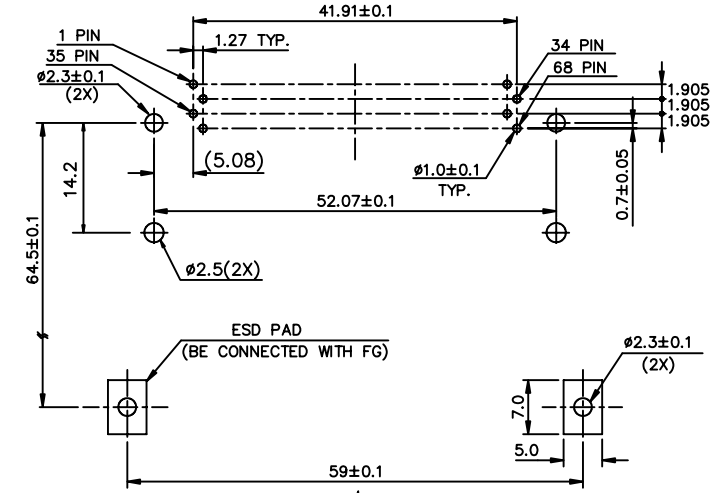
PRODUCT NO.	DIM "M"	DIM "P"
52581-130CAH	3	4.8
52581-150CAH	5	4.8
52581-130CAHLF	3	4.8
52581-150CAHLF	5	4.8



- NOTES:
- MATERIAL
 - HEADER ASS'Y:
PLASTIC :HOUSING ...LCP UL94V-0 BLACK
PIN :COPPER ALLOY
 - EJECT MECHANISM ASS'Y:
PLASTIC :GUIDE:POLYPHTHARAMID, BLACK
PUSH ROD:POLYPHTHARAMID, BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
 - FINISH (PIN)
UNDER PLATING :0.5 um MIN. Ni
CONTACT AREA :0.1 um MIN. GOLD OVER
0.5 um MIN. Pd-Ni
SOLDER TAIL : 2.5 um MIN. Sn-Pb
: 2.5 um MIN. PURE Sn (FOR -*****LF)

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

- RETENTION FORCE HOLD DOWN VERSUS HEADER: 15N MIN.
- P.C.B. THICKNESS 1.6mm.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code				tolerance unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
rev.	ecn no.	dr	date	linear	±0.30	projection 	title		
A	T00288	W L	09/21/00					SINGLE DECK,R/A EJECTOR	
B	T03-0326	W L	08/14/03	angles	± 2°		TYPE I/II/III		
C	N05-0135	W B	05/27/05						
		dr	WENDY CHEN	01/19/00	unit	product family		code	
		enr	LEIF SHEN	01/19/00	mm/inch	POMCA			
		chr	JOSEPH HSIAO	01/19/00	scale	size		sheet	
		appd	LELAND WANG	01/19/00	1:1	A3		1 OF 1	
sheet	revision	C					dwg no.		
index	sheet	1					52581		
									</